



## SSC8336GN4

### Dual N-Channel Enhancement MOSFET

#### Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>
30V	±20V	15mΩ@10V	12A
		18.5mΩ@4V5	

#### Description

The SSC8336GN4 uses advanced trench technology to provide excellent RDS(ON) and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

**100% UIS + ΔVDS + Rg Tested!**

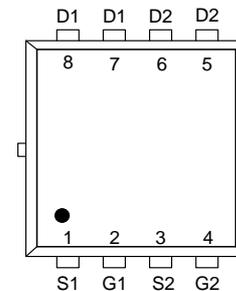
#### Applications

- Inverter
- DC-DC Converter
- Half and Full Bridge Topology

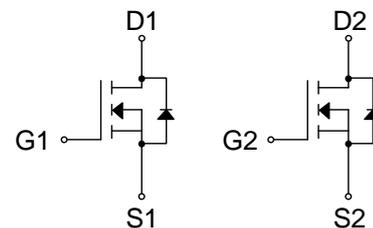
#### Ordering Information

Device	Package	Shipping
SSC8336GN4	PDFN3.3X3.3-8L	5000/Reel

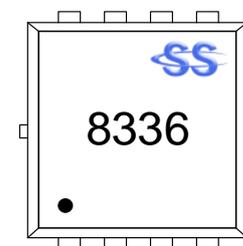
#### Pin configuration



**PDFN3.3x3.3-8L (Top View)**



**Pin Configuration**



**Marking**



### ➤ Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
$V_{DSS}$	Drain-to-Source Voltage	30	V	
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V	
$I_D$	Continuous Drain Current	$T_C = 25^{\circ}\text{C}$	12	A
		$T_C = 100^{\circ}\text{C}$	8	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	35	A	
$I_{AS}$	Avalanche Current <sup>b</sup> L = 0.1mH	21	A	
$E_{AS}$	Avalanche Energy <sup>b</sup> L = 0.1mH	22	mJ	
$I_D$	Continuous Drain Current <sup>a</sup>	$T_A = 25^{\circ}\text{C}$	10	A
		$T_A = 70^{\circ}\text{C}$	7.5	A
$P_D$	Power Dissipation <sup>c</sup>	$T_C = 25^{\circ}\text{C}$	19	W
		$T_C = 100^{\circ}\text{C}$	8	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	$T_A = 25^{\circ}\text{C}$	2.5	W
		$T_A = 70^{\circ}\text{C}$	0.9	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$	
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$	

### ➤ Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	55	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	6.5	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

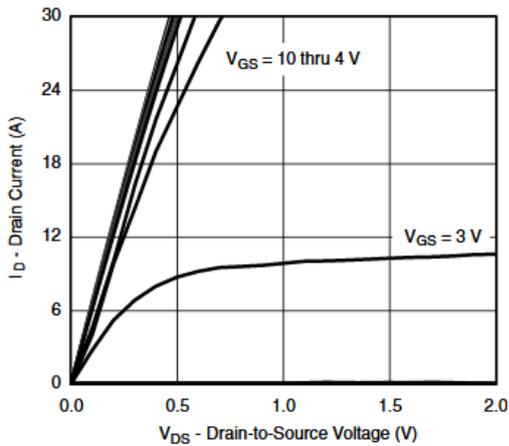


➤ **Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

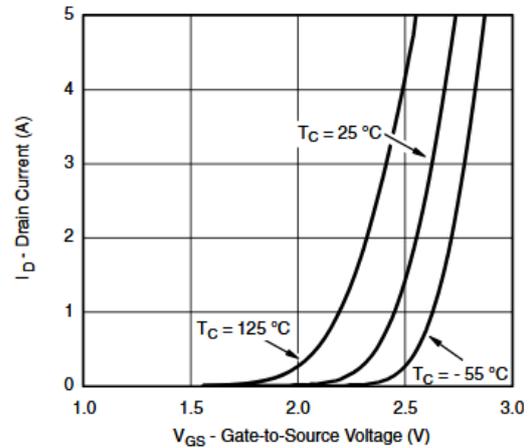
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1	1.5	2	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A		15	18	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A		18.5	27	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 3.6A		18		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A		0.95	1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		700		pF
Output Capacitance	C <sub>OSS</sub>			115		
Reverse Transfer Capacitance	C <sub>RSS</sub>			54		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 10A		13		nC
Gate to Source Charge	Q <sub>GS</sub>			2		
Gate to Drain Charge	Q <sub>GD</sub>			1.4		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, R <sub>L</sub> = 2.5Ω, R <sub>GEN</sub> = 1Ω		10		ns
Rise Time	T <sub>r</sub>			8		
Turn-off Delay Time	T <sub>D(OFF)</sub>			21		
Fall Time	T <sub>f</sub>			7		



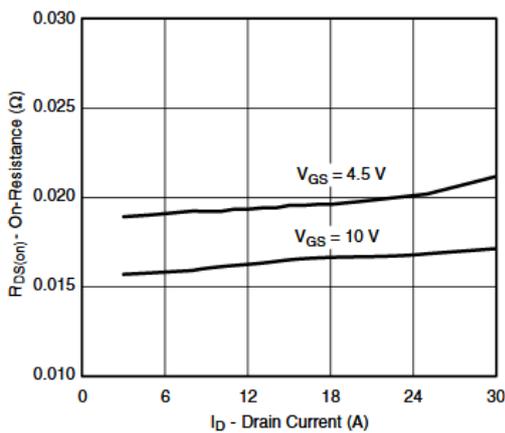
➤ Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)



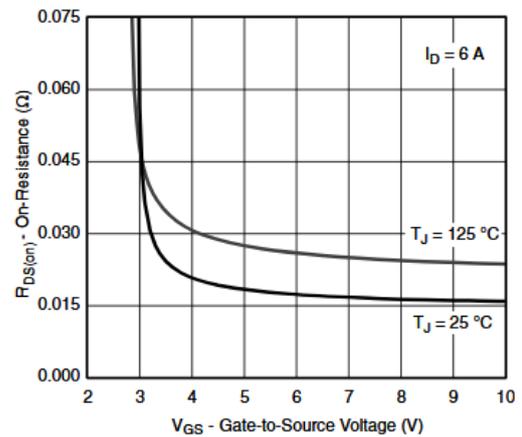
**Output Characteristics**



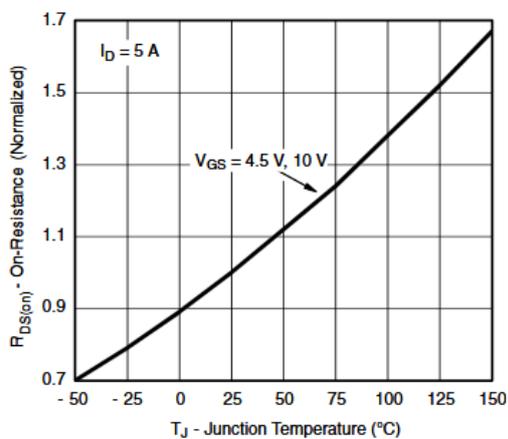
**Transfer Characteristics**



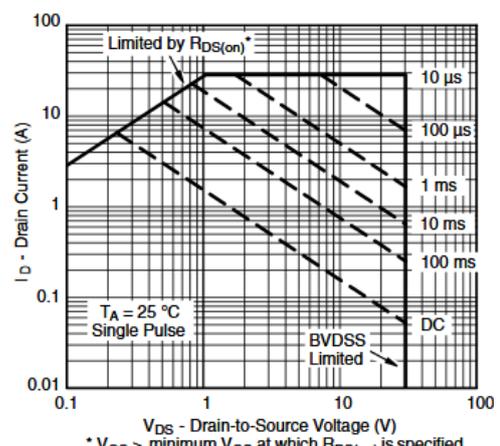
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

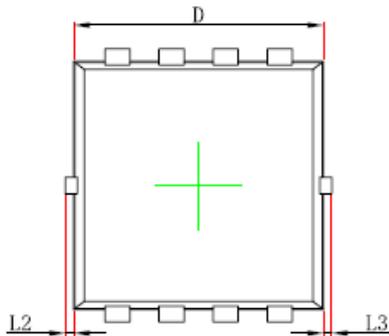


**On-Resistance vs. Junction Temperature**

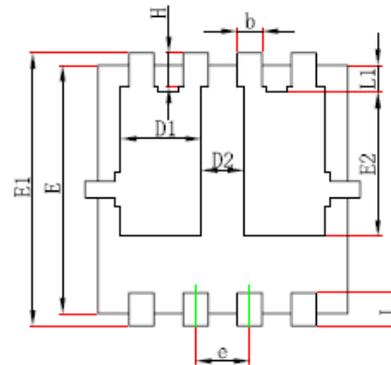


**Safe Operating Area, Junction-to-Ambient**

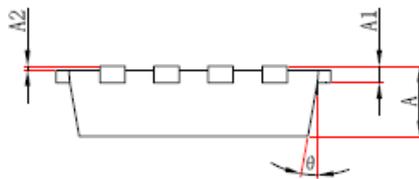
## ➤ Package Information



Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°



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